

N and P-Channel Enhancement Mode Power MOSFET

Description

The HM4606B uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

N-Channel

 $V_{DS} = 30V, I_{D} = 6.5A$

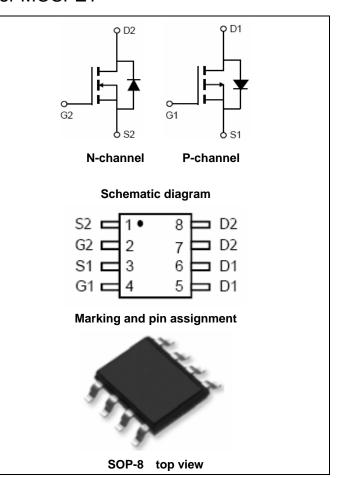
 $R_{DS(ON)}$ < 30m Ω @ V_{GS} =10V

P-Channel

 $V_{DS} = -30V, I_{D} = -7A$

 $R_{DS(ON)}$ < 33m Ω @ V_{GS} =-10V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM4606B	HM4606B	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parame	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V _{DS}	30	-30	V	
Gate-Source Voltage		V _{GS}	±20	±20	V	
Continuous Drain Current	T _A =25℃	1	6.5	-7	^	
Continuous Drain Current	T _A =70°C	l _D	5.4	-5.8	Α	
Pulsed Drain Current (Note 1)		I _{DM}	30	-30	А	
Maximum Power Dissipation T _A =25℃		P _D	2.0	2.0	W	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55 To 150	-55 To 150	$^{\circ}$ C	

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance,Junction-to-Ambient (Note2)	$R_{\theta JA}$	P-Ch	62.5	°C/W



N-CH Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V_{GS} =0V I_D =250 μ A	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} =30 V , V_{GS} =0 V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D =250 μ A	1	1.5	2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =10V, I_D =6A	-	20	30	mΩ
Forward Transconductance	g FS	V_{DS} =5 V , I_{D} =6 A	15	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V,	-	255	-	PF
Output Capacitance	C _{oss}	F=1.0MHz	-	45	-	PF
Reverse Transfer Capacitance	C _{rss}	T = 1.01VII 12	-	35	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	4.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =15 V , R_L =2.5 Ω	-	2.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{GEN} =3 Ω	-	14.5	-	nS
Turn-Off Fall Time	t _f		-	3.5	-	nS
Total Gate Charge	Qg	\/ -15\/ -6^	-	13	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =15V, I_{D} =6A, V_{GS} =10V	-	5.5	-	nC
Gate-Drain Charge	Q_{gd}	v GS-10 v	-	3.5	-	nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	8.0	1.2	V



P-CH Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA	
Gate-Body Leakage Current	I_{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D =-250 μ A	-1.0	-1.4	-1.8	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-6.5A	-	28	33	mΩ	
Forward Transconductance	g FS	V_{DS} =-5 V , I_{D} =-6.5 A	10	-	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C_{lss}	V _{DS} =-15V,V _{GS} =0V,	-	520	ı	PF	
Output Capacitance	C _{oss}	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz	-	100	ı	PF	
Reverse Transfer Capacitance	C _{rss}	r = 1.0ivii iz	-	65	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	7.5	-	nS	
Turn-on Rise Time	t _r	V_{DD} =-15V, R_L =2.3 Ω	-	5.5	-	nS	
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =-10 V , R_{GEN} =6 Ω	-	19	-	nS	
Turn-Off Fall Time	t _f		-	7	-	nS	
Total Gate Charge	Qg	\/ - 15\/ - 6.5A	-	9.2	-	nC	
Gate-Source Charge	Q _{gs}	V_{DS} =-15V, I_{D} =-6.5A V_{GS} =-10V	-	1.6	-	nC	
Gate-Drain Charge	Q _{gd}	v _{GS} 10 v	-	2.2	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-6.5A	-	-	-1.2	V	

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



N- Channel Typical Electrical and Thermal Characteristics (Curves)

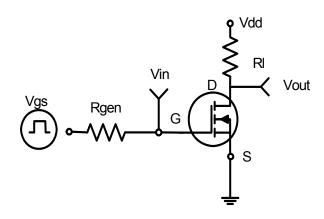


Figure 1:Switching Test Circuit

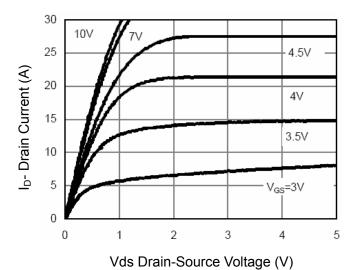


Figure 3 Output Characteristics

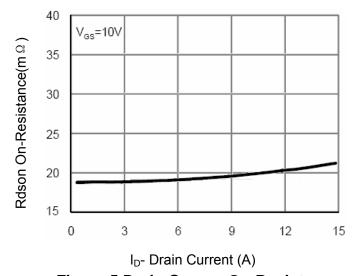


Figure 5 Drain-Source On-Resistance

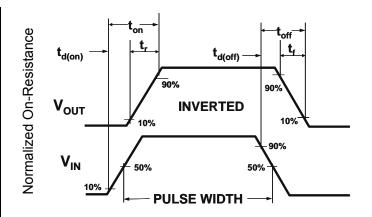


Figure 2:Switching Waveforms

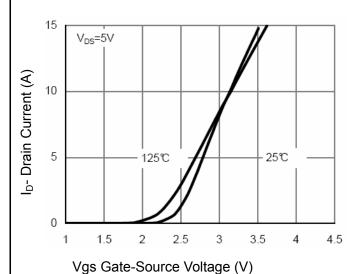


Figure 4 Transfer Characteristics

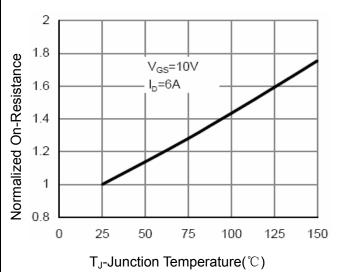


Figure 6 Drain-Source On-Resistance



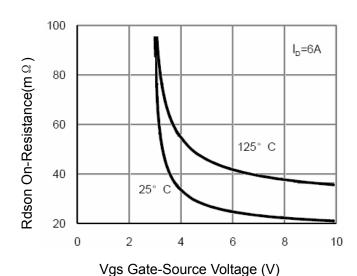


Figure7 Rdson vs Vgs

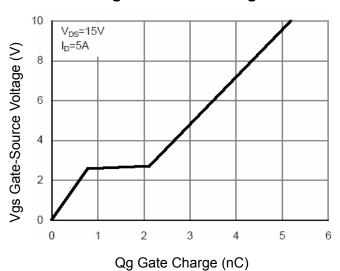


Figure 9 Gate Charge

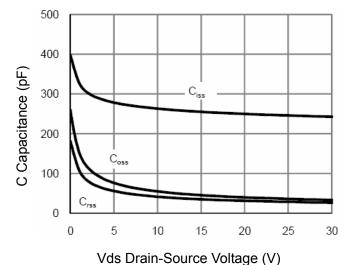
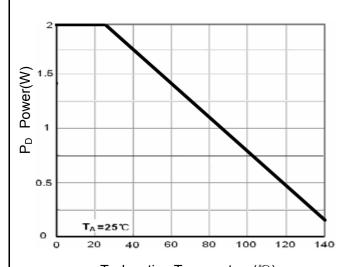


Figure 11 Capacitance vs Vds



 T_J -Junction Temperature($^{\circ}$ C) Figure 8 Power Dissipation

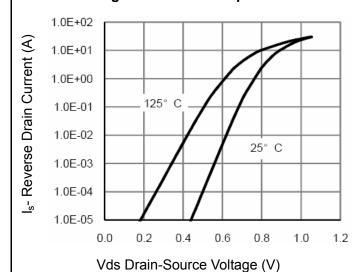
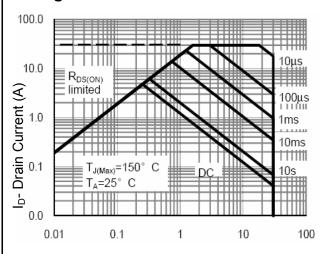


Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)
Figure 12 Safe Operation Area



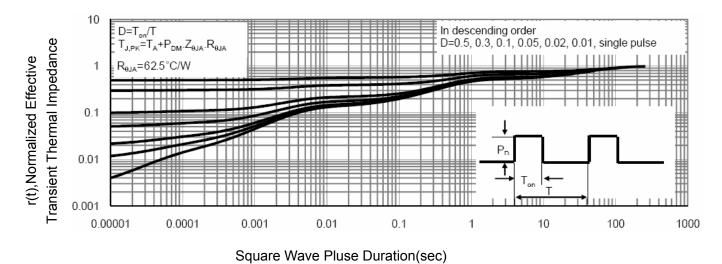


Figure 13 Normalized Maximum Transient Thermal Impedance



P- Channel Typical Electrical and Thermal Characteristics (Curves)

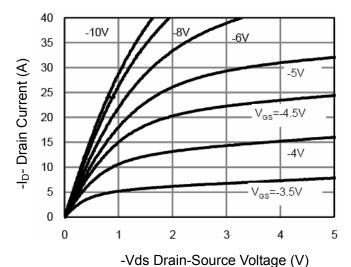
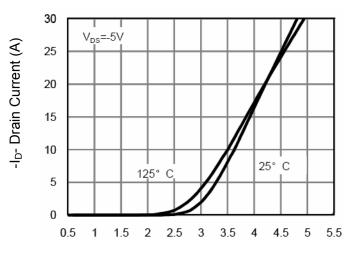


Figure 1 Output Characteristics



-Vgs Gate-Source Voltage (V)

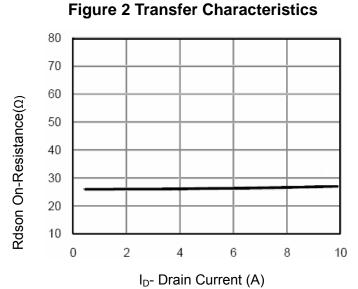


Figure 3 Rdson- Drain Current

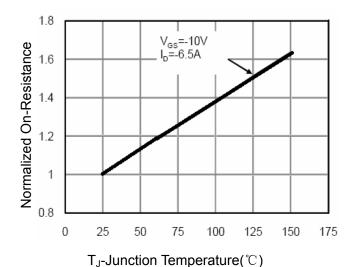


Figure 4 Rdson-Junction Temperature

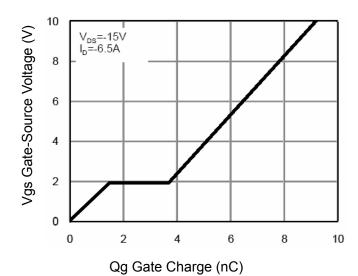


Figure 5 Gate Charge

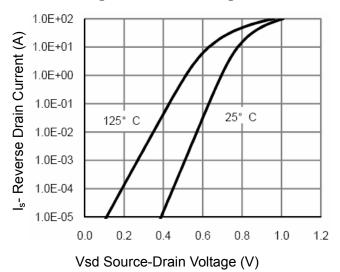


Figure 6 Source- Drain Diode Forward



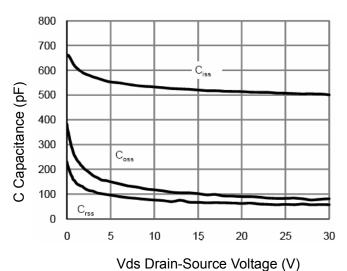


Figure 7 Capacitance vs Vds

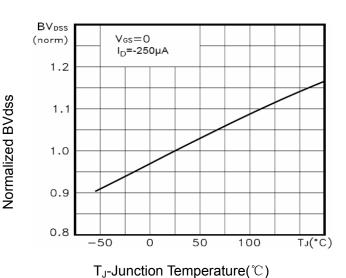


Figure 9 BV_{DSS} vs Junction Temperature

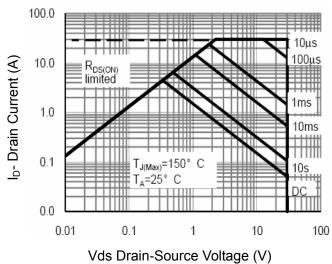


Figure 8 Safe Operation Area

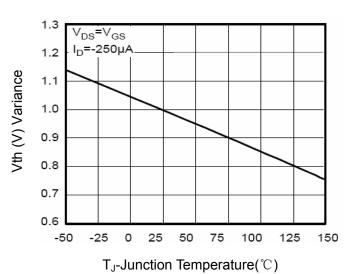


Figure 10 V_{GS(th)} vs Junction Temperature

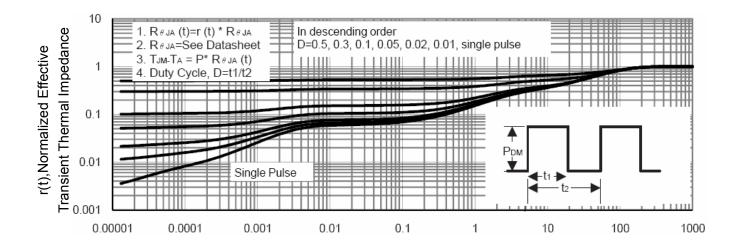
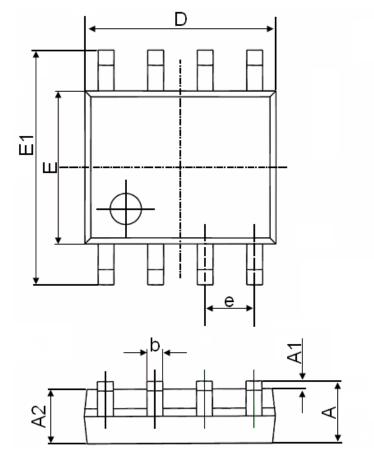


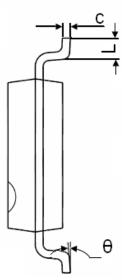
Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)



SOP-8 Package Information





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050(BSC)		
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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